

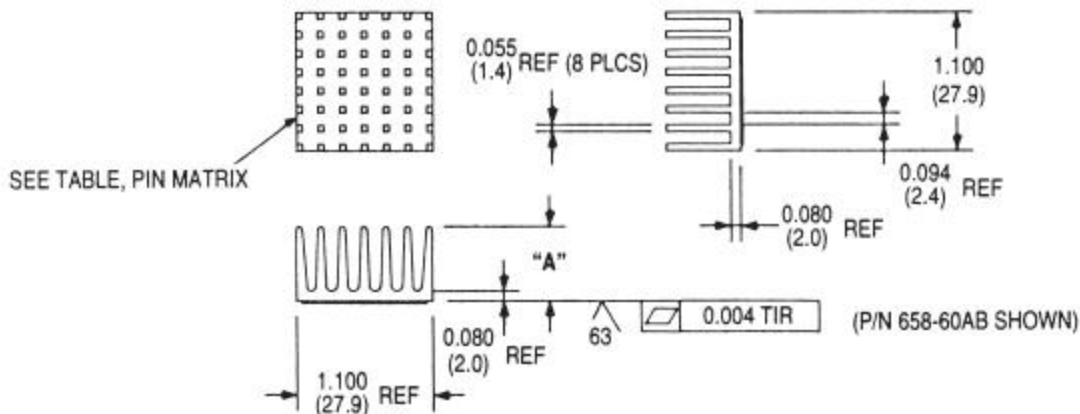
wakefield-vette

658 SERIES

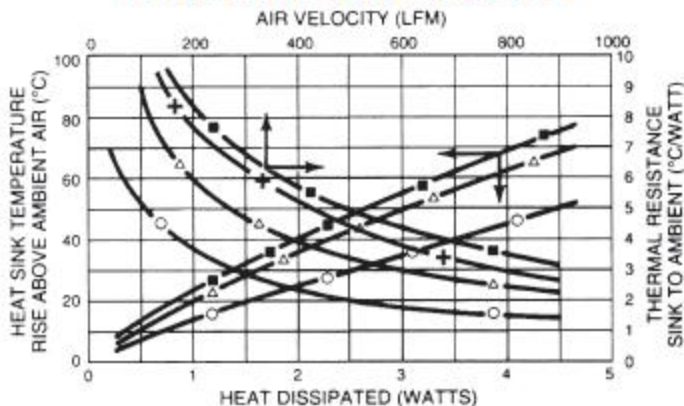
Omnidirectional Pin Fin Heat Sink for BGAs and PowerPC™

Standard P/N	Base Dimensions in. (mm)	Dimension "A" in. (mm)	Typical Applications	Heat Sink Finish	Weight lbs. (grams)
658-25AB	1.100 (27.9) sq	0.250 (6.4)	27mm BGA	Black Anodized	0.013 (5.67)
658-35AB	1.100 (27.9) sq	0.350 (8.9)	27mm BGA	Black Anodized	0.015 (6.70)
658-45AB	1.100 (27.9) sq	0.450 (11.4)	27mm BGA	Black Anodized	0.019 (8.50)
658-60AB	1.100 (27.9) sq	0.600 (15.2)	27mm BGA	Black Anodized	0.031 (14.17)

Notes: 1. Optional factory preapplied pressure-sensitive adhesive. See Page 3



NATURAL AND FORCED CONVECTION CHARACTERISTICS



KEY: ■ 658-25AB + 658-35AB △ 658-45AB ○ 658-60AB

Mouser Electronics

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